

SOT1143-1

plastic low profile fine-pitch ball grid array package; 417 balls

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|--|
| Terminal position code | B (bottom) |
| Package type descriptive code | LFBGA417 |
| Package type industry code | LFBGA417 |
| Package style descriptive code | LFBGA (low profile fine-pitch ball grid array) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| IEC package outline code | --- |
| JEDEC package outline code | --- |
| JEITA package outline code | --- |
| Mounting method type | S (surface mount) |
| Issue date | 19-6-2009 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-------|-----|------|-------|------|
| D | package length | 18.85 | - | 19 | 19.15 | mm |
| E | package width | 18.85 | - | 19 | 19.15 | mm |
| A | seated height | 1.07 | - | 1.39 | 1.6 | mm |
| A ₂ | package height | 0.92 | - | 1.06 | 1.2 | mm |
| e | nominal pitch | - | - | 0.8 | - | mm |
| n ₂ | actual quantity of termination | - | - | 417 | - | |



2. Package outline

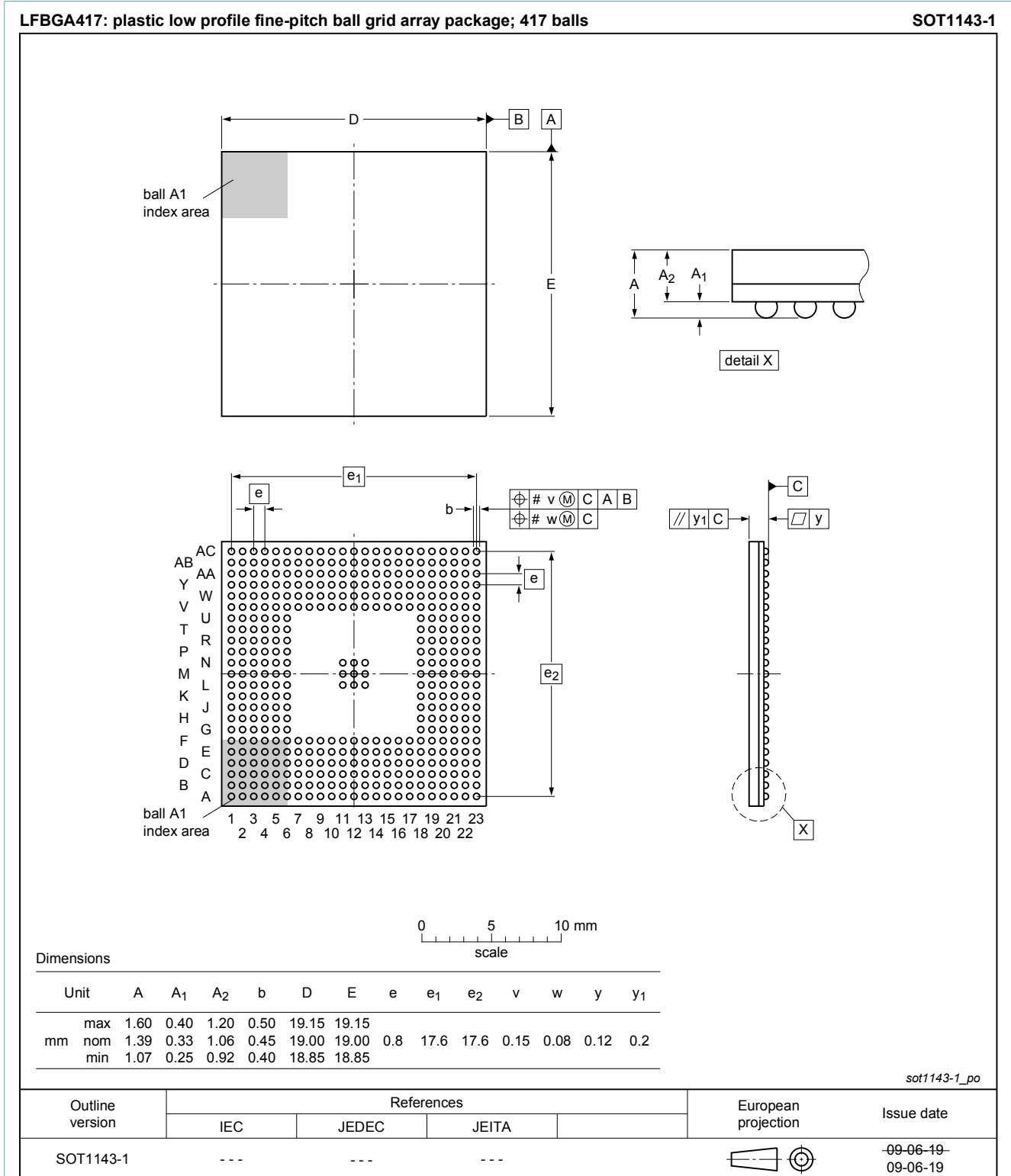


Fig. 1. Package outline LFPGA417 (SOT1143-1)

3. Legal information

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